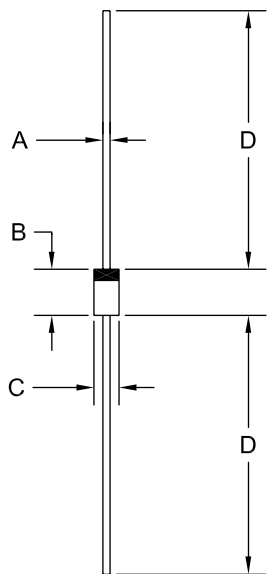


# Package Details - DO-41

## Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.028	0.034	0.71	0.86
B	0.160	0.205	4.06	5.21
C	0.080	0.107	2.03	2.72
D	1.000	-	25.40	-

DO-41 (REV: R1)

**Lead Code:**  
Cathode band

R1

### Packing options:

#### Bulk - Packing Code: D

D = White corrugated box with black conductive coating (surface resistivity of  $<10^5$  ohms per square).

**Bulk Packing Quantity:** 2,000

#### Tape and Reel - Packing Code: A

A = Axial taped and reeled in accordance with EIA-296-E. If required, individual reels placed in poly antistatic coated bags (surface resistivity of  $>10^9$  and  $<10^{13}$  ohms per square).

**Tape and Reel Packing Quantity:** 5,000

# Material Composition Specification

## DO-41 Glass Case

Device average mass ..... 335 mg

Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	.024%	.08	Si	7440-21-3	.017%	.058	174
				Ag	7440-22-4	.007%	.022	66
leadframe	dumet	12.24%	41.0	Cu	7440-50-8	1.958%	6.561	19,584
				Ni	7440-02-0	5.753%	19.271	57,525
				Fe	7439-89-6	4.529%	15.171	45,286
	metal alloy	68.68%	230.08	Fe	7439-89-6	48.077%	161.058	480,769
Cu				7440-50-8	20.604%	69.026	206,044	
encapsulation	glass	16.63%	55.7	PbO	1317-36-8	9.977%	33.422	99,768
				SiO <sub>2</sub>	14808-60-7	6.651%	22.282	66,512
plating	matte tin	2.40%	8.04	Sn	7440-31-5	2.398%	8.033	23,978
				Pb	7439-92-1	.002%	.006	17
ink		.028%	.089	tributyl-phosphate	126-73-8	.017%	.056	168
				carbon black	1333-96-4	.004%	.013	38
				phenol	108-95-2	.001%	.001	14
				Proprietary	---	.006%	.019	58

### Disclaimer

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# Material Composition Specification

## DO-41 Epoxy Case

Device average mass ..... 336 mg

Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.227%	0.76	Si	7440-21-3	0.226%	0.758	2,256
				Au	7440-57-5	.001%	.004	12
die attach	high temperature solder	0.66%	2.23	Pb	7439-92-1	0.614%	2.06	6,140
				Sn	7440-31-5	.033%	0.11	333
				Ag	7440-22-4	.017%	.06	167
leadframe	metal alloy	82.52%	277	Fe	7439-89-6	.074%	0.25	744
				Cu	7440-50-8	82.444%	277	824,444
encapsulation	EMC	13.69%	46	SiO <sub>2</sub>	14808-60-7	9.31%	31.28	93,100
				epoxy resin	29690-82-2	2.738%	9.2	27,382
				phenol resin	9003-35-4	1.369%	4.6	13,691
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	0.137%	0.46	1,369
				Br	14808-60-7	0.137%	0.46	1,369
plating	matte tin	2.89%	9.7	Sn	7440-31-5	2.884%	9.69	28,841
				Pb	7439-92-1	.001%	.005	14
ink		.014%	.05	2-propenic acid	53192-18-0	.006%	.021	63
				Al	7429-90-5	.002%	.006	18
				silica	112945-52-5	.0003%	.001	3
				methanone	947-19-3	.0003%	.001	3
				isoamyl 4-benzoate	21245-01-2	.005%	.017	50

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